

N-Channel Super Junction Power MOSFET $\ensuremath{\,\mathrm{IV}}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- •Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

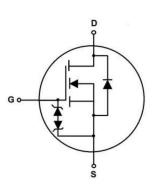
Package Marking And Ordering Information

Device	Device Package	Marking
NCE70N290I	TO-251	NCE70N290I

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	VDS	700	V
Gate-Source Voltage (V _{DS} =0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDs=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	13	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	9.1	A
Pulsed drain current ^(Note 1)	I _{DM (pluse)}	39	A
Maximum Power Dissipation(Tc=25°C)	PD	124	W
Derate above 25°C		0.82	W/°C
Single pulse avalanche current (Note 2)	I _{AS}	1.5	A
Reverse diode dv/dt, $V_{DS} \leqslant 480 V, I_{SD} < I_D$	dv/dt	15	V/ns
Drain Source voltage slope, $V_{DS} \leqslant 480 V$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C

V _{DS min@Tjmax}	750	V
Rds(on)typ.	260	mΩ
ID	13	А
Qg	16.5	nC



Schematic diagram

TO-251

Wuxi NCE Power Co., Ltd



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.20	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250uA	700			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =700V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I _{DSS}	V _{DS} =700V,V _{GS} =0V			50	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250$ uA	3		4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =10V, I _D =6.5A		260	295	mΩ
Dynamic Characteristics					· ·	
Gate Resistance	Rg	F=1MHZ, D-S short		17		Ω
Input Capacitance	Clss			1082		pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1MHz		35		pF
Reverse Transfer Capacitance	C _{rss}			9		pF
Total Gate Charge	Qg			16.5		nC
Gate-Source Charge	Q _{gs}	V_{DS} =520V, I_{D} =6.5A,		3.9		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		3.5		nC
Gate plateau voltage	Vgp			4.6		V
Switching times					· · ·	
Turn-on Delay Time	t _{d(on)}			13		nS
Turn-on Rise Time	tr	V_{DD} =520V, I_{D} =6.5A,		8		nS
Turn-Off Delay Time	t _{d(off)}	R_G =4 Ω , V_{GS} =10V		50		nS
Turn-Off Fall Time	t _f			8		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T 0500			13	А
Pulsed-Source-drain current(Body Diode)	I _{SDM}	T _c =25°C			39	А
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =13A,V _{GS} =0V		0.9	1.1	V
Reverse Recovery Time	t _{rr}			220		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I⊧6.5A,		1.1		uC
Peak reverse recovery current	Irrm	di/dt=100A/µs		10		А

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^\circ\!\mathrm{C}$,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

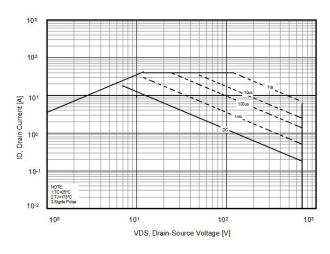


Figure3. Output characteristics

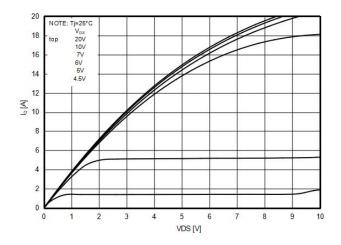
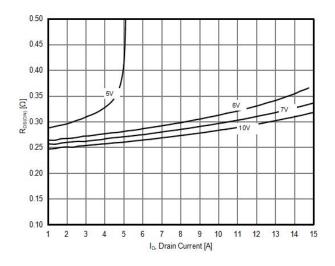


Figure5. Static drain-source on resistance



102 Reverse Drain Current [A] 101 25°C 100 10-1 a d 10-2 10-3 0.2 0.4 0.6 0.8 1.0 1.2 1.4 1.6 V_{SD,} Source-Drain Voltage [V]

Figure2. Source-Drain Diode Forward Voltage

Figure4. Transfer characteristics

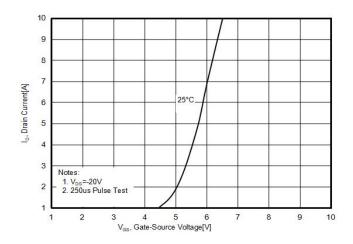


Figure6. RDS(ON) vs Junction Temperature

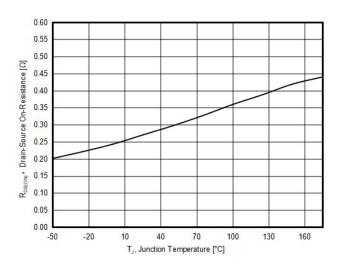




Figure 7. BV_{DSS} vs Junction Temperature

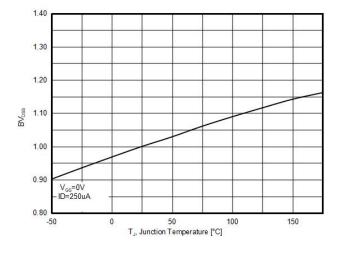


Figure9. Gate charge waveforms

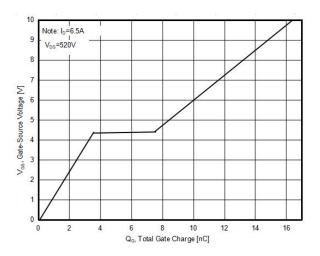


Figure8. Maximum I_D vs Junction Temperature

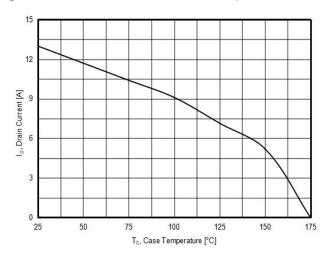
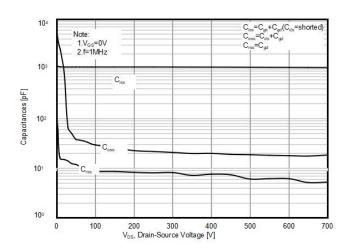


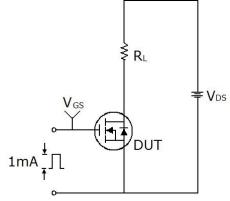
Figure10. Capacitance

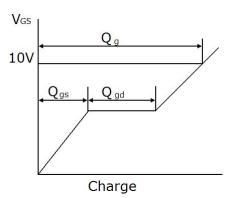




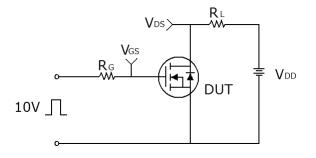
Test circuit

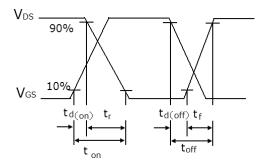
1) Gate charge test circuit & Waveform



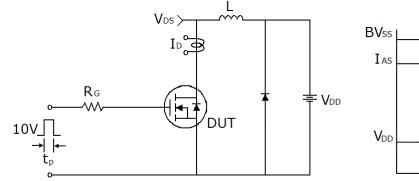


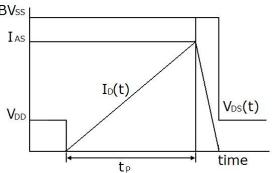
2) Switch Time Test Circuit:





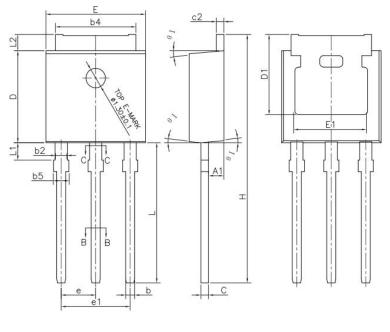
3) Unclamped Inductive Switching Test Circuit & Waveforms

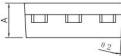






TO-251-P Package Information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.20	2.35	0.087	0.093	
A1	0.90	1.10	0.035	0.043	
b	0.56	0.69	0.022	0.027	
b1	0.55	0.65	0.022	0.026	
b2	0.77	0.90	0.030	0.035	
b3	0.76	0.86	0.030	0.034	
b4	5.23	5.43	0.206	0.214	
С	0.46	0.59	0.018	0.023	
c1	0.45	0.55	0.018	0.022	
c2	0.46	0.59	0.018	0.023	
D	6.00	6.20	0.236	0.244	
D1	5.20	-	0.205	-	
E	6.50	6.70	0.256	0.264	
E1	4.60	5.00	0.181	0.197	
e	2.24	2.34	0.088	0.092	
e1	4.47	4.67	0.176	0.184	
Н	16.18	16.78	0.637	0.661	
L	9.00	9.60	0.354	0.378	
L1	0.95	1.35	0.037	0.053	
L2	0.90	1.25	0.035	0.049	



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